

00mm

## RIGID-FLEX STACK UP

FLEX AREA 1		RIGID AREA		FLEX AREA 2	
		Top Paste Stencil			
		Top Solder Mask, .025 mm, Blue			
		Layer 1, Top Copper, 0.5 oz base, .018 mm			
		Dielectric, 0.038 mm, Prepreg 106 (IT 180A)			
		Layer 2, GND (Plane 1), 0.5 oz base, 0.018 mm			
		Dielectric, 0.150 mm, FR4			
		Layer 3, Rigid (Signal 1), 0.5 oz base, 0.018 mm			
Flex Top, MCL Plus 110, 0.051 mm	Dielectric, 0.140 mm, Prepreg 1080NF (IT 180A)		Flex Coverlay Top, MCL Plus 110, 0.051 mm		
		Layer 4, Flex (Signal 2), 0.5 oz base, 0.018 mm			
		Dielectric (Core), 0.050 mm, Polyimide RF775 H/H			
Layer 5, Flex (Signal 3), 0.5 oz base, 0.018 mm				Flex Coverlay Bottom, MCL Plus 110, 0.051mm	
Flex Bottom, MCL Plus 110, 0.051mm	Dielectric, 0.140 mm, Prepreg 1080NF (IT 180A)				
Layer 6, 3V3 (Plane 2), 0.5 oz base, 0.018 mm					
Dielectric, 0.150 mm, FR4					
Layer 7, GND (Plane 3), 0.5 oz base, 0.018 mm					
Dielectric, 0.038 mm, Prepreg 106 (IT 180A)					
Layer 8, Bottom Copper, 0.5 oz base, 0.018 mm					
Bottom Solder Mask, 0.025 mm, Blue					
Bottom Paste Stencil					

## BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	0.9000 mm
Board overall dimensions:	84.0000 mm x 94.0000 mm		
Min track/spacing:	0.1500 mm / 0.1500 mm	Min hole diameter:	0.1600 mm
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

COSMIC		
Sheet:		
File: PM1C_Rev_1_2.kicad_pcb		
<b>Title: PM1C PCB Fabrication Drawing</b>		
Size: B	Date: 2024-07-25	Rev: 1
KiCad E.D.A. 8.0.2		Id: 1/1

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